



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2025-06-23
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	APMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
SCT055W65G3-4AG	T3TM*BRF5LVF	A	Z8GA	2025-06-23
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	6080	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information			
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles	
Not Applicable	Not Applicable		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0

Package designator	Package size	Number of instances	Shape
SIP	15.8x21	4	Through-hole
Comment			
Comment	A0TM TO247-4		

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
Exemption Id.	Description	
8(e)	8(e) - Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)	

QueryList : California Prop65 list, dated 17th Nov 2023				Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen				false
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen				true
Substance	amount in product (mg)	Application	ppm in product	
Nickel	23.963	alloy	3941	
Lead	2.403	solder	395	

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014					Response
QUERY					Response
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products					true
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products					false
Hazardous substance					
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE	
X	O	O	O	O	
Soft solder					
Homogeneous Material(s) containing Lead					

QueryList : REACH-7th November 2024					Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH					true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product	
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH					false
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material	



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Tin,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

QueryList:Stockholm Convention Persistent Organic Pollutants (POP)	Response
Product is compliant with Annex A, B and C of Stockholm Convention Persistent Organic Pollutants	true

QueryList: EU Ship Recycling Regulation No. 1257/2013	Response
Product contains hazardous materials listed in Annex II of EU Ship Recycling Regulation No.1257/2013 and 2009/16/EC Directive	True
The material present in the product is:	Lead

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration :						Mfr Item Name	T3TM*BRFSLVF		6080.0000		7000000.0	999998.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.390	mg	supplier	die	Silicon(Si)	7440-21-3		0.014	mg	4130	2
	M-011 Other inorganic materials			California 65	die	Silicium carbide	409-21-2		3.177	mg	937168	523
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.058	mg	17109	10
				supplier	metallisation	Copper(Cu)	7440-50-8		0.008	mg	2360	1
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.050	mg	14749	8
				supplier	metallisation	Silver(Ag)	7440-22-4		0.051	mg	15044	8
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.006	mg	1770	1
				supplier	metallisation	Vanadium(V)	7440-62-2		0.002	mg	590	0
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.009	mg	2655	1
				supplier	passivation	Silicon oxide	7631-86-9		0.015	mg	4425	2
Leadframe	M-004 Copper and its alloys	4781.030	mg	supplier	alloy	Copper (Cu)	7440-50-8		4752.335	mg	993998	781634
				supplier	alloy	Iron(Fe)	7439-89-6		4.782	mg	1000	787
				supplier	alloy	Nickel (Ni)	7440-02-0		23.913	mg	5002	3933
Soft solder	Solder	2.516	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temperat	2.403	mg	955087	395
				supplier	solder	Tin(Sn)	7440-31-5		0.050	mg	19873	8
				supplier	solder	Silver(Ag)	7440-22-4		0.063	mg	25040	10
Bonding wires	M-003 Aluminum and its alloys	1.286	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.286	mg	1000000	212
Bonding wires 2	M-003 Aluminum and its alloys	0.322	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.322	mg	1000000	53
Encapsulation	M-011 Other inorganic materials	1248.874	mg	supplier	mold compound	Silica vitreous	60676-86-0		978.042	mg	783139	160862
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		187.211	mg	149904	30791
				supplier	mold compound	Phenol resin	9003-35-4		62.404	mg	49968	10264
				supplier	mold compound	Triphenylphosphine	603-35-0		9.985	mg	7995	1642
				supplier	mold compound	Bismuth compound	7440-69-9		4.992	mg	3997	821
	supplier	mold compound	Carbon black	1333-86-4		6.240	mg	4997	1026			